GS5484 21V, 3A, 340KHz Synchronous Step-Down DC/DC Converter

Product Description

The GS5484 is a synchronous step-down DC/DC converter that provides wide 5V to 21V input voltage range and 3A continuous load current capability.

Other features such as integrated Boot-Diode, programmable Soft-Start, total fault-free protection and 94% conversion efficiency at 5V/2A output make GS5484 ideally to be used in portable consumer electronics.

The GS5484 is available in an 8-pin SOIC package, provides a very compact system solution and good thermal conductance.

Features

- Wide Input Voltage from 5V to 21V
- 3A Output Current
- Adjustable Output Voltage from 0.922V to 15V
- 90/80mΩ integrated Power MOSFET
- High Efficiency Up to 94% at 5V/2A Output
- Fixed 340KHz Switching Frequency.
- Current Mode PWM Operation
- Soft-Start Function
- Current limit
- Input Under Voltage Lockout
- Over-Temperature Protection
- 1.1mA Quiescent Current
- Thermal Enhanced PSOP-8 Package
- RoHS Compliant, 100%Pb & Halogen Free

Applications

- Set-Top-Box
- DVD, LCD Displays
- Networking Device
- Distributed Power System



Functional Block Diagram



Typical Applications



Table 1 recommended Component Selection

| Vout | R1 | R2 | R3 | C3 | L1 | C2 | C1 |
|------|-------|-----|------|-------|----------------|----------------------|---------------|
| 5.0V | 44.2K | 10K | 7.5K | 3.3nF | 10 μ H | 22 x2+0.1 μ F | 10 x2+0.1 μ F |
| 3.3V | 26.1K | 10K | 6.8K | 3.3nF | 10 μ H | 22 x2+0.1 μ F | 10 x2+0.1 μ F |
| 2.5V | 17K | 10K | 5.6K | 3.3nF | 6.8 μ Η | 22 x2+0.1 μ F | 10 x2+0.1 μ F |
| 1.8V | 9.4K | 10K | 4.7K | 3.3nF | 6.8 μ H | 22 x2+0.1 μ F | 10 x2+0.1 μ F |
| 1.2V | 3.9K | 10K | 3.9K | 3.3nF | 4.7 μ Η | 22 x2+0.1 μ F | 10 x2+0.1 μ F |
| 1.0V | 1.3K | 15K | 3.3K | 3.3nF | 3.3 μ Η | 22 x2+0.1 μ F | 10 x2+0.1 μ F |

Packages & Pin Assignments

O R

CONDUC

| | | GS5484PSF (PSOP-8) | | |
|------|--------------------|---|--|--|
| | | 8 7 6 5 Exposed 1 1 1 1 2 3 4 | | |
| Name | me No. Description | | | |
| BS | 1 | High Side Gate Drive Boost Input. A 10nF or greater capacitor must be connected from this pin to SW. It can boost the gate drive to fully turn on the internal high side NMOS. | | |
| Vin | 2 | Power Supply Input Pin. Drive 5V to 21V voltage to this pin to power on this chip. Connecting a 10 μ F ceramic bypass capacitor between V _{IN} and GND to eliminate noise. | | |
| SW | 3 | Power Switching Output. It is the output pin that internal high side NMOS switching to supply power. | | |
| GND | 4 | Ground Pin. Connecting this pin to exposed pad. | | |
| FB | 5 | Voltage Feedback Input Pin. Connecting FB and Vout with a resistive voltage divider. | | |
| COMP | 6 | Compensation Pin. This pin is used to compensate the regulation control loop. Connect a series RC network from COMP pin to GND. | | |
| EN | 7 | Enable Input Pin. This pin provides a digital control to turn the converter on or off. Connect to V_{IN} with a 100K Ω resistor for self-startup. | | |
| SS | 8 | Soft-Start Input Pin. This pin controls the soft-start period. Connect a capacitor from SS to GND to set the soft start period. | | |



Ordering Information



| Order Number | Package Code | Package | Quantity |
|--------------|--------------|---------|----------------------|
| GS5484PSF | PS | PSOP-8 | 4000 PCS/Tape & Reel |

Marking Information



Absolute Maximum Ratings (Note 1)

| Parameter | Symbol | Мах | Units |
|-------------------------------------|------------------|--|-------|
| Input Supply Voltage | VIN | -0.3 to +25 | V |
| SW Voltage | V _{SW} | -1 ~(V _{IN} +0.3) | V |
| Boost Voltage | V _{BS} | (V _{SW} – 0.3)~(V _{SW} +5) | V |
| All Other Pins Voltage | | -0.3 to +6 | V |
| Maximum Junction Temperature | TJ | 150 | °C |
| Storage Temperature | T _{STG} | -65~150 | °C |
| Lead Temperature (Soldering 10 sec) | | 260 | °C |
| ESD Rating (Human Body Mode) | HBM | 4 | KV |
| ESD Rating (Machine Mode) | MM | 300 | V |

Recommended Operating Conditions (Note 2)

| Parameter | Symbol | Мах | Units |
|----------------------|-----------------|----------|-------|
| Input Supply Voltage | V _{IN} | 5 to +21 | V |
| Output Voltage | Vout | 0.922~15 | V |
| Ambient Temperature | T _A | -40~85 | °C |
| SOP-8 (Exposed Pad) | θ _{JA} | 50 | °C/W |
| SOP-8 (Exposed Pad) | θ _{Jc} | 10 | °C/W |

Note 1: Stresses exceed those ratings may damage the device. Note 2: If out of its operation conditions, the device is not guaranteed to function.



Electrical Characteristics

(V_IN=12V, T_A=25 $^\circ\!\mathrm{C}$, unless otherwise specified)

| Parameter | Test Conditions | Min | Тур | Мах | Units |
|---|--|-------|-------|------|-------|
| VIN Input Supply Voltage | | 5 | | 21 | V |
| VIN Supply Current | V _{EN} =2.0V | | 1.1 | | mA |
| VIN Shutdown Supply Current | V _{EN} =0V | | | 25 | μA |
| Feedback Voltage | $5V{\leq}V_{IN}{\leq}21V$ | 0.904 | 0.922 | 0.94 | V |
| High-Side MOSFET RDS(ON) | | | 90 | | mΩ |
| Low-Side MOSFET RDS(ON) | | | 80 | | mΩ |
| High-Side MOSFET Leakage Current | V _{EN} = 0V V _{SW} = 0V | | | 10 | μA |
| Current Limit | | 5 | | | Α |
| COMP to Current sense Transconductance | | | 4.2 | | A/V |
| Error Amplifier Transconductance | $\Delta I_{COMP} = \pm 10 \mu A$ | | 800 | | μA/V |
| Error Amplifier Voltage Gain | | | 400 | | V/V |
| Oscillation frequency | | | 340 | | KHz |
| Short Circuit Oscillation Frequency | $V_{FB} = 0V$ | | 100 | | KHz |
| Maximum Duty Cycle | $V_{FB} = 0.8V$ | | 90 | | % |
| Minimum On Time | | | 200 | | ns |
| Input UVLO Threshold | VIN Rising | | 4.75 | | V |
| Under Voltage Lockout Threshold Hysteresis | | | 400 | | mV |
| Soft-Start Period | $C_{SS} = 0.1 \mu F$ | | 15 | | ms |
| EN Input Threshold Voltage | V _{EN} Rising | | 1.5 | | V |
| EN Input low current | | | 0.1 | | μA |
| Thermal Shutdown Threshold | | | 160 | | °C |
| Thermal Shutdown hysteresis | | | 20 | | °C |



Typical Operating Characteristics

 $V_{IN}{=}12V,~V_{OUT}{=}5.0V,~C1$ = 10uF , C2 = 22uF, L1 = 15uH, T_A = +25 $^\circ\!\mathrm{C}$, unless otherwise noted.



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Typical Operating Characteristics(cont.)









Figure11. Load Transient













Function Description

The GS5484 is a constant frequency current mode step-down synchronous DC/DC converter. It regulates input voltage from 5V to 21V, down to an output voltage as low as 0.922V and can provide 3A of continuous load current.

Control Loop

During normal operation, the output voltage is sensed at FB pin through a resistive voltage divider and amplified through the error amplifier. The voltage of error amplifier output pin – COMP is compared to the switch current to controls the RS latch. At each cycle, the high side NMOS would be turned on when the oscillator sets the RS latch and would be turned off when current comparator resets the RS latch. When the load current increases, the FB pin voltage drops below 0.922V, it causes the COMP voltage increase until average inductor current arrive at new load current.

Enable

The GS5484 EN pin provides digital control to turn on/turn off the regulator. When the voltage of EN exceeds the threshold voltage, the regulator starts the soft start function. If the EN pin voltage is below than the threshold voltage, only the bandgap voltage is alive. If the EN pin voltage is below than the shutdown threshold voltage, the regulator will be disable and into the shutdown mode.

Maximum Load Current

The maximum load current decreases at lower input voltage because of large IR drop on the high side switch and low side switch. The slope compensation signal reduces the peak inductor current as a function

of the duty cycle to prevent sub-harmonic oscillations at duty cycles greater than 50%.

Input Under Voltage Lockout

When the GS5484 power on, the internal circuits are held inactive until V_{IN} exceeds the input UVLO threshold voltage. And the regulator will be disabled when V_{IN} below the input UVLO threshold voltage.

Short Circuit Protection

The GS5484 provides short circuit protection function to prevent the device damage from short condition. When the output short to ground, the oscillator frequency is reduced to prevent the inductor current increasing beyond the current limit. In the meantime, the current limit is also reduced to lower the short current. Once the short condition is removed, the frequency and current limit will return to normal.

Over Temperature Protection

The GS5484 incorporates an over temperature protection circuit to protect itself from overheating. When the junction temperature exceeds the thermal shutdown threshold temperature, the regulator will be shutdown.

Compensation

The stability of the feedback circuit is controlled through COMP pin. The compensation value of the application circuit is optimized for particular requirements. If different conversions are requires, some of the components may need to be changes to ensure stability.

Application Information

Output Voltage Setting

The output voltage V_{OUT} is set using a resistive divider from the output to FB. The FB pin regulated voltage is

$$V_{OUT} = 0.922 \times \left(1 + \frac{R1}{R2}\right) V$$

0.922V. Thus the output voltage is:

R2 recommended value is $10k\Omega$, so R1 is determined by: R1 = $10.83 \times (V_{OUT} - 0.922) k\Omega$ Table 1 lists recommended values of R1 and R2 for most used output voltage.

Table 2 Recommended Resistance Values

| VOUT | R1 | R2 |
|------|--------|------|
| 5V | 44.2kΩ | 10kΩ |
| 3.3V | 26.1kΩ | 10kΩ |
| 2.5V | 17.0kΩ | 10kΩ |
| 1.8V | 9.4kΩ | 10kΩ |

Place resistors R1 and R2 close to FB pin to prevent stray pickup.



Input Capacitor Selection

The use of the input capacitor is controlling the input voltage ripple and the MOSFETS switching spike voltage. Because the input current to the step-down converter is discontinuous, the input capacitor is required to supply the current to the converter to keep the DC input voltage. The capacitor voltage rating should be 1.25 times to 1.5 times greater than the maximum input voltage.

The input capacitor ripple current RMS value is calculated as:

$$I_{\rm IN(RMS)} = I_{\rm OUT} \times \sqrt{D} \times (1 - D)$$

Where D is the duty cycle of the power MOSFET.

A low ESR capacitor is required to keep the noise minimum. Ceramic capacitors are better, but tantalum or low ESR electrolytic capacitors may also suffice. When using tantalum or electrolytic capacitors, a 0.1uF ceramic capacitor should be placed as close to the IC as possible.

Output Capacitor Selection

The output capacitor is used to keep the DC output voltage and supply the load transient current. Low ESR capacitors are preferred. Ceramic, tantalum or low ESR electrolytic capacitors can be used, depends on the output ripple requirement. Add a 100uF or 470uF Low ESR electrolytic capacitor when operated in high input voltage range ($V_{IN} > 20V$). It can improve the device's stability. The output ripple voltage ΔV_{OUT} is described as:

$$\Delta \mathbf{I} = \frac{\mathbf{V}_{\text{OUT}}}{\text{Fosc} \times \mathbf{L}} \times \left(1 - \frac{\mathbf{V}_{\text{OUT}}}{\text{Vin}}\right)$$
$$\Delta \mathbf{V}_{\text{OUT}} = \Delta \mathbf{I} \times \left(\text{Resr} + \frac{1}{8 \times \text{Fosc} \times \text{Cout}}\right)$$

Where ΔI is the peak-to-peak inductor ripple current, FOSC is the switching frequency, L is the inductance value, V_{IN} is the input voltage, V_{OUT} is the output voltage, RESR is the equivalent series resistance value of the output capacitor, and the C_{OUT} is the output capacitor. When using the ceramic capacitors, the RESR can be ignored and the output ripple voltage ΔV_{OUT} is shown as:

$$\Delta V_{\rm OUT} = \frac{\Delta I}{8 \times Fosc \times C_{\rm OUT}}$$

When using tantalum or electrolytic capacitors, typically 90% of the output voltage ripple is contributed by the ESR of output capacitors. the output ripple voltage ΔV_{OUT} can be estimated as:

$$\Delta V_{OUT} = \Delta I \times R_{ESR}$$

Output Inductor Selection

The output inductor is used for store energy and filter output ripple current. But the trade-off condition often happens between maximum energy storage and the physical size of the inductor. The first consideration for selecting the output inductor is to make sure that the inductance is large enough to keep the converter in the continuous current mode. That will lower ripple current and results in lower output ripple voltage. A good rule for determining the inductance is set the peak-to-peak inductor ripple current ΔI almost equal to 30% of the maximum load current. Then the minimum inductance can be calculated with the following equation:

$$\begin{split} \Delta I &= 0.3 \times \mathrm{Iout}(max) \\ L &\geq \left(V_{\mathrm{IN}} - V_{\mathrm{OUT}} \right) \times \left(\frac{V_{\mathrm{OUT}}}{Fosc \times \Delta I \times V_{\mathrm{IN}}} \right) \end{split}$$

Where V_{IN} is the maximum input voltage.



Compensation Components Selection



Selecting the appropriate compensation value by following procedure: 1. Calculate the R4 value with the following equation:

 $R4 < \frac{2\pi \times C_{OUT} \times 0.1 \times Fosc \times V_{OUT}}{2\pi \times C_{OUT}}$

 $G_{\text{EA}} \times G\!cs \times V_{\text{REF}}$

where G_{EA} is the error amplifier voltage gain, and G_{CS} is the current sense gain.

2. Calculate the C5 value with the following equation:

$$C5 > \frac{4}{2\pi \times R4 \times 0.1 \times Fosc}$$

3. If the COUT ESR zero is less than half of the switching frequency, use C6 to cancel the ESR zero:

$$C6 = \frac{C_{OUT} \times R_{ESR}}{R4}$$

PCB Layout Recommendation

The device's performance and stability is dramatically affected by PCB layout. It is recommended to follow these general guidelines show bellow:

- 1. Place the input capacitors, output capacitors as close to the device as possible. Trace to these capacitors should be as short and wide as possible to minimize parasitic inductance and resistance.
- 2. Place V_{IN} bypass capacitors close to the V_{IN} pin.
- 3. Place feedback resistors close to the FB pin.
- 4. Place compensation components close to the COMP pin.
- 5. Keep the sensitive signal (FB, COMP) away from the switching signal (SW).
- 6. The exposed pad of the package should be soldered to an equivalent area of metal on the PCB. This area should connect to the GND plane and have multiple via connections to the back of the PCB as well as connections to intermediate PCB layers. The GND plane area connects to the exposed pad should be maximized to improve thermal performance.
- 7. Multi-layer PCB design is recommended.



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Package Dimension

PSOP-8









| | Dimensions | | | | | | |
|--------|--------------------|-------|--------|-------------|------|--|--|
| | Millim | eters | | Millimeters | | | |
| SYMBOL | MIN | MAX | SYMBOL | MIN | MAX | | |
| Α | 4.80 | 5.00 | C3 | 0.00 | 0.09 | | |
| A1 | 0.356 | 0.456 | C4 | 0.203 0.233 | | | |
| A2 | 1.27 | TYP | D | 1.05 TYP | | | |
| A3 | 0.345 | TYP | D1 | 0.40 0.80 | | | |
| В | 3.80 4.00 | | R1 | 0.20 | TYP | | |
| B1 | 5.80 | 6.20 | R2 | 0.20 TYP | | | |
| B2 | B2 5.00 TYP | | | 17° | ТҮР | | |
| С | 1.30 | 1.60 | θ2 | 13º TYP | | | |
| C1 | 0.55 | 0.65 | θ3 | 0°~8° | | | |
| C2 | 0.55 | 0.65 | θ4 | 4°~12° | | | |



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